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(12) **United States Design Patent**
Yamada et al.

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (8) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; 174/52.1, 174/52.2, 52.4; 257/666, 669, 675, 676, 678, 690, 692, 696, 697, 730, 787; 361/773, 820; 438/64, 65

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,752,182 A	*	5/1998	Nakatsuka et al.	455/333
5,949,294 A	*	9/1999	Kondo et al.	331/68
D416,236 S	*	11/1999	Kobayashi et al.	D13/182
5,991,162 A	*	11/1999	Saso	361/760
D444,132 S		6/2001	Iwanishi et al.	
6,383,835 B1	*	5/2002	Hata et al.	438/65
D476,962 S		7/2003	Yoshihira et al.	
6,713,868 B2	*	3/2004	Ueno	257/730

FOREIGN PATENT DOCUMENTS

JP	1046274	8/1999
JP	1067223	4/2000
JP	1078599-1	7/2000
JP	1131942	1/2002
JP	1171699	4/2003

OTHER PUBLICATIONS

Kinseki, KSS Products Catalog, SAW Filter (LSFB30–190–004M0), p. 71. Mar. 2000.

Dempa Shimbun, An Infineon Technologies Tuner IC (TUA6120), Jul. 2002.

* cited by examiner

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(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and right side perspective view of a semiconductor device, showing our new design;

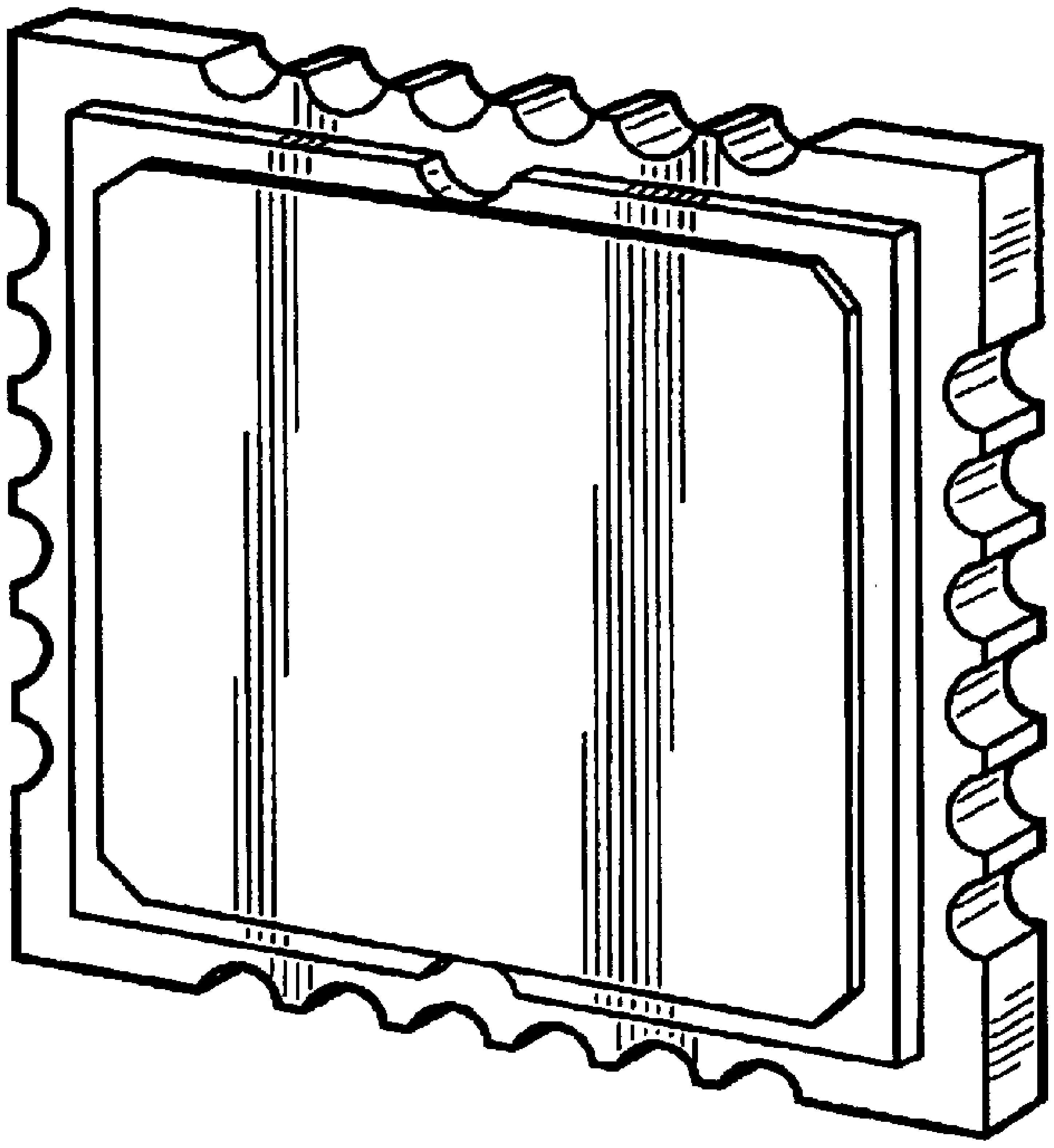
FIG. **2** is a top plan view thereof; the opposite side being a mirror image thereof;

FIG. **3** is a front elevational view thereof;

FIG. **4** is a right side elevational view thereof; the opposite side being a mirror image thereof; and,

FIG. **5** is a rear elevational view thereof.

1 Claim, 2 Drawing Sheets



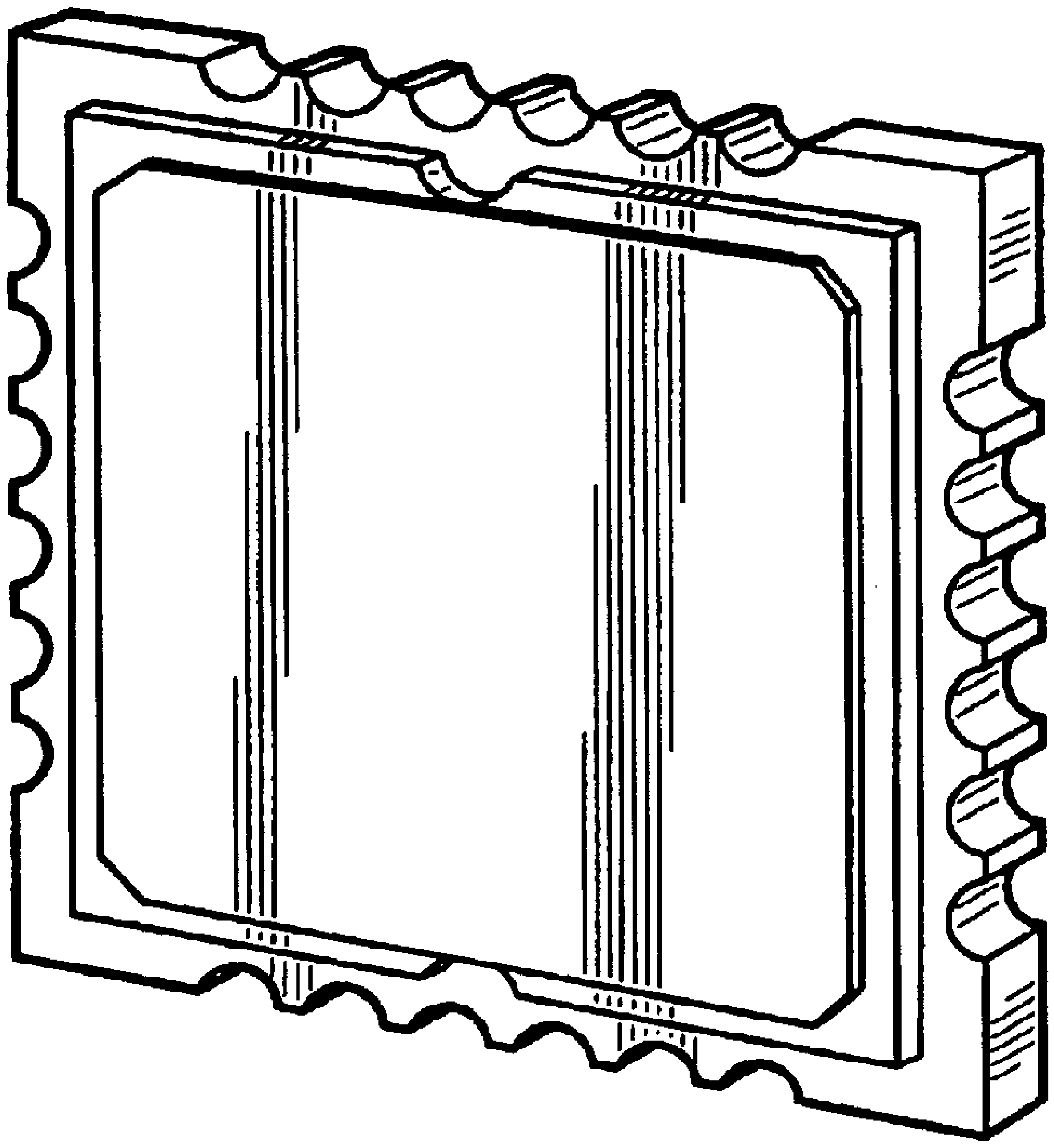


FIG.1

FIG.2

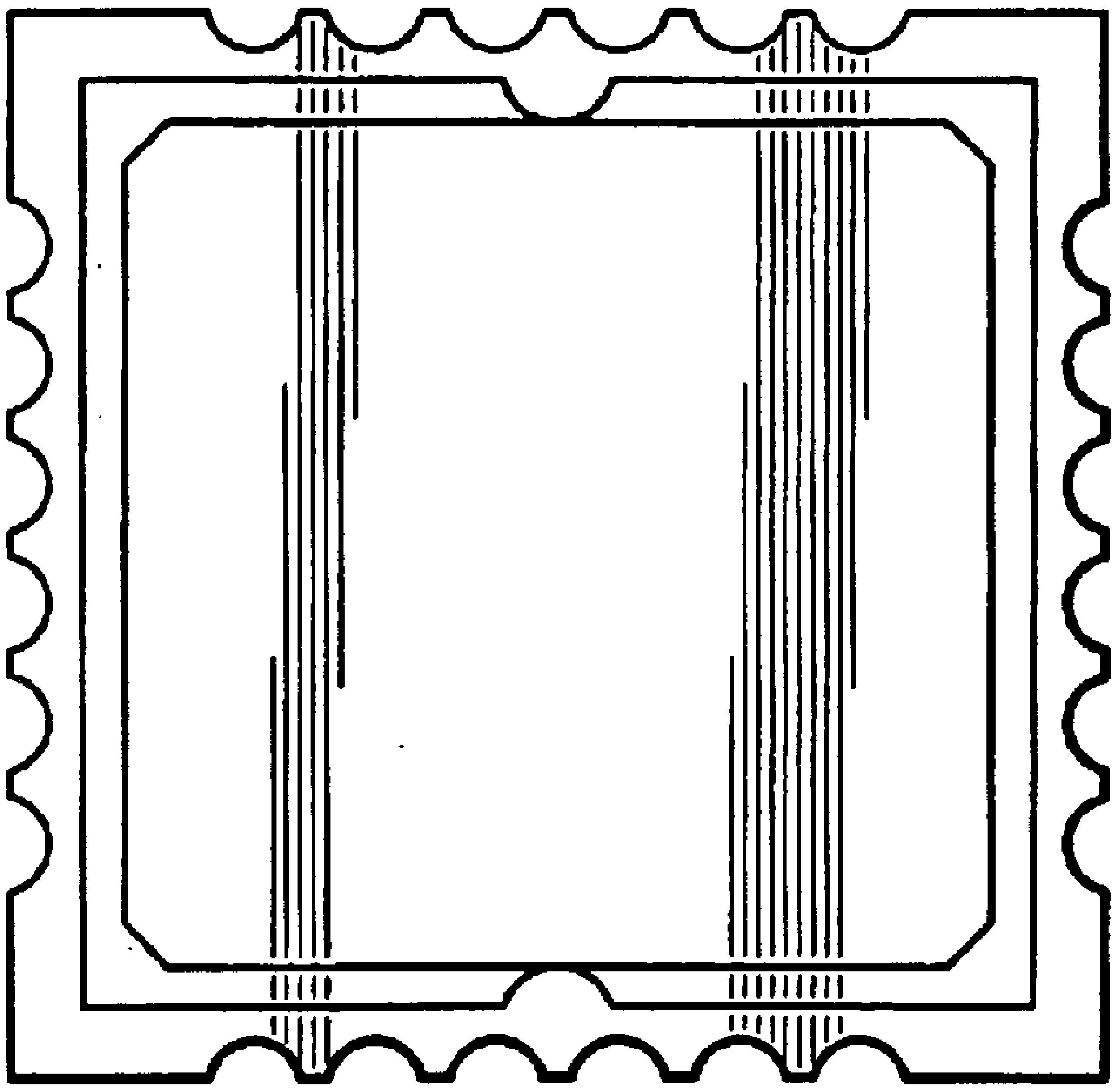


FIG.3

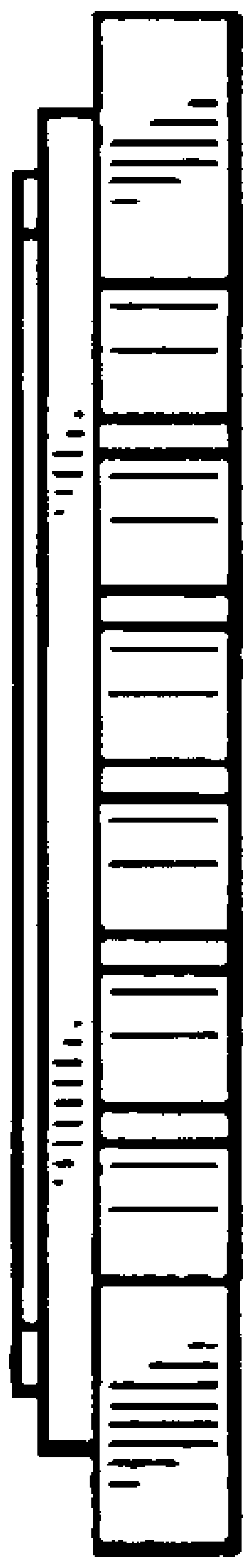


FIG.4

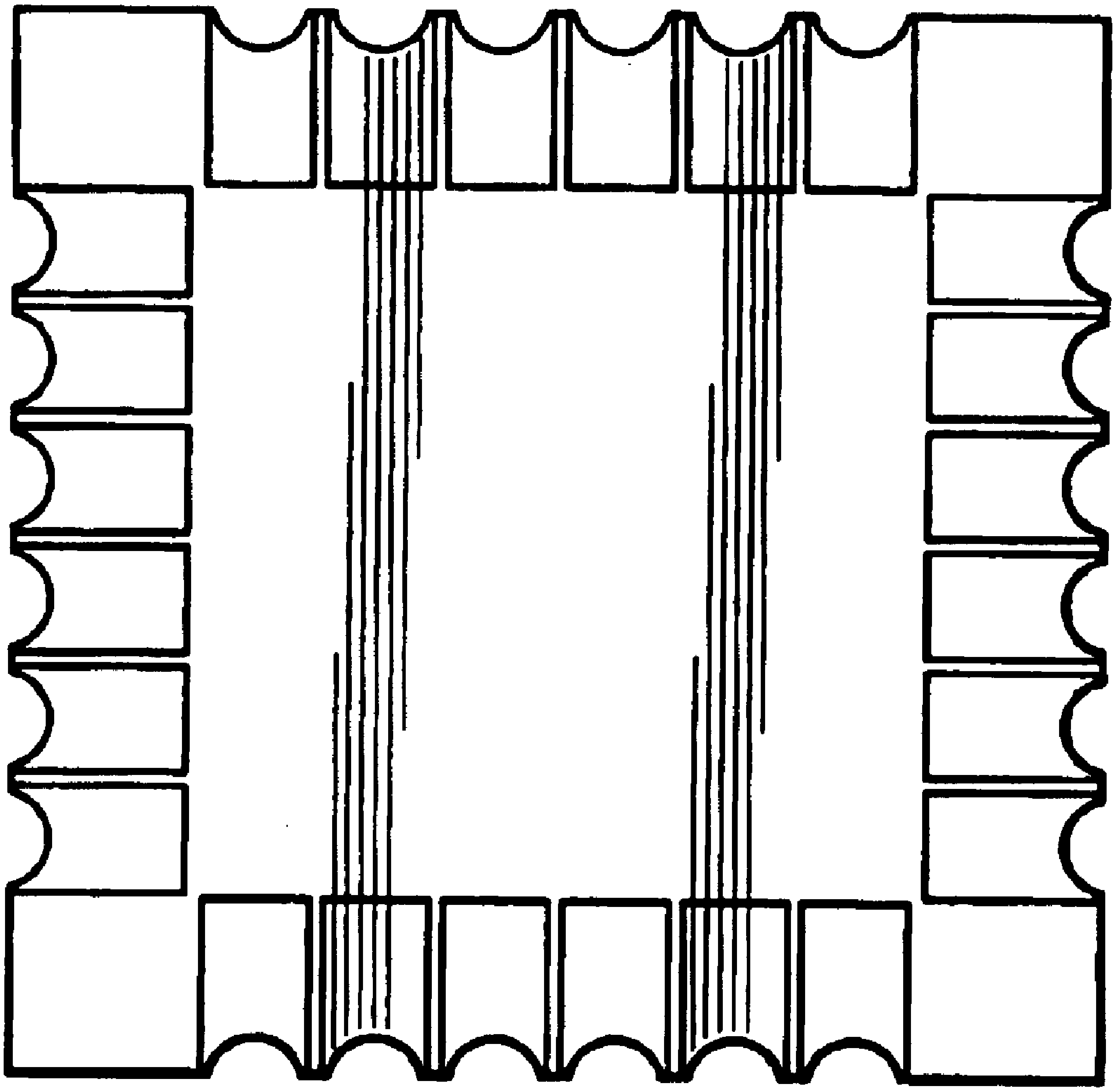


FIG.5